

# Yoshio Mita

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/8930964/publications.pdf>

Version: 2024-02-01

83  
papers

747  
citations

840776

11  
h-index

580821

25  
g-index

83  
all docs

83  
docs citations

83  
times ranked

683  
citing authors

#	ARTICLE	IF	CITATIONS
1	PbS Colloidal Quantum Dots/ZnO/Si Hybrid Photodiode with Various Reverse Bias Voltages. IEEJ Transactions on Sensors and Micromachines, 2022, 142, 8-12.	0.1	0
2	Design and Fabrication of an Electrochemical Chip for Liquid-Phase Transmission Electron Microscopy. Microscopy (Oxford, England), 2022, , .	1.5	2
3	Two-Dimensionally Arrayed Double-Layer Electrode Device Which Enables Reliable and High-Thoroughput Electrorotation. , 2021, , .		1
4	High Throughput 16 NM Nanogap by Variable Shaped Beam Method Using F7000S-VD02 EB Lithography. , 2021, , .		0
5	Drop-In Test Structure to Evaluate Residual Stress in Conformally Grown Films. IEEE Transactions on Semiconductor Manufacturing, 2021, 34, 270-277.	1.7	0
6	Improvement of ZnO/Si Heterojunctions With a Coaxial Circular Transmission Line Model Applicable to Both Ohmic and Schottky. IEEE Transactions on Semiconductor Manufacturing, 2021, 34, 256-261.	1.7	3
7	Manufacturing of 3D Helical Microswimmer by AFM Micromanipulation for Microfluidic Applications. IEEE Transactions on Semiconductor Manufacturing, 2021, 34, 248-255.	1.7	1
8	3D micro fractal pipettes for capillary based robotic liquid handling. Review of Scientific Instruments, 2020, 91, 086104.	1.3	2
9	Coaxial Circular Test Structure Applicable to both Ohmic and Schottky Characteristics for ZnO/Si Heterojunctions Assessment. , 2020, , .		1
10	Circularly polarized vacuum ultraviolet coherent light generation using a square lattice photonic crystal nanomembrane. Optica, 2020, 7, 855.	9.3	6
11	A Rapid, Reliable and Less-destructive On-chip Mass Measurement for 3D Composite Material Testing Microstructures. , 2020, , .		1
12	Drop-in test structure chip to visualize residual stress of Ru/Cu film grown by atomic layer deposition and supercritical fluid deposition. , 2020, , .		1
13	Micro-scale Electrostatic Attach-detach Device for Self-reconfigurable Modular Robotic System. , 2020, , .		5
14	Tunable third harmonic generation in the vacuum ultraviolet region using dielectric nanomembranes. APL Photonics, 2020, 5, 066103.	5.7	12
15	On-Chip CMOS-MEMS-Based Electroosmotic Flow Micropump Integrated With High-Voltage Generator. Journal of Microelectromechanical Systems, 2020, 29, 86-94.	2.5	11
16	An On-Chip Micromachined Test Structure to Study the Tribological Behavior of Deep-RIE MEMS Sidewall Surfaces. IEEE Transactions on Semiconductor Manufacturing, 2020, 33, 187-195.	1.7	7
17	Area-selective Cu Film Growth on TiN and SiO <sub>2</sub> by Supercritical Fluid Deposition. IEEJ Transactions on Sensors and Micromachines, 2020, 140, 31-36.	0.1	2
18	Tunable Third Harmonic Vacuum Ultraviolet Coherent Light Generation Using Dielectric Nanomembranes. , 2020, , .		0

#	ARTICLE	IF	CITATIONS
19	Damage Assessment Structure of Test-Pad Post-Processing on CMOS LSIs. , 2019, , .		1
20	PbS Quantum Dot / ZnO Nanowires Hybrid Test Structures for Infrared Photodetector. , 2019, , .		6
21	Stick-to-Analyze Zeta Potential Measurement Chip with Integrated Electroosmotic Micropump and Liquid Flow Sensor. , 2019, , .		3
22	A zero-power sensing MEMS shock sensor with a latch-reset mechanism for multi-threshold events monitoring. Sensors and Actuators A: Physical, 2019, 295, 1-10.	4.1	32
23	The surface responsivity of a SnO <sub>2</sub> thin film gas sensing device for the highly sensitivity. The Proceedings of the Symposium on Micro-Nano Science and Technology, 2019, 2019.10, 20am2PN315.	0.0	0
24	Influence of Pretreatment on Adhesion Quality of Supercritical-fluid-deposited Cu Film on Si. Sensors and Materials, 2019, 31, 2481.	0.5	2
25	A Device for Localized Measurement of Small Particles with Electrode-Integrated Small Pores. IEEJ Transactions on Sensors and Micromachines, 2019, 139, 271-276.	0.1	0
26	Noninvasive Localization of IGBT Faults by High-Sensitivity Magnetic Probe With RF Stimulation. IEEE Transactions on Instrumentation and Measurement, 2018, 67, 745-753.	4.7	21
27	Microscale ultrahigh-frequency resonant wireless powering for capacitive and resistive MEMS actuators. Sensors and Actuators A: Physical, 2018, 275, 75-87.	4.1	5
28	High-uniformity centimeter-wide Si etching method for MEMS devices with large opening elements. Japanese Journal of Applied Physics, 2018, 57, 04FC03.	1.5	6
29	Integrated 30 V switching driver circuit fabricated by mesa isolation postprocess of standard 5ÅV CMOS LSI for MEMS actuator applications. Microsystem Technologies, 2018, 24, 503-510.	2.0	4
30	Progress and opportunities in high-voltage microactuator powering technology towards one-chip MEMS. Japanese Journal of Applied Physics, 2018, 57, 04FA05.	1.5	7
31	Study on silicon device of microrobot system for heterogeneous integration. , 2018, , .		3
32	An on-chip test structure for studying the frictional behavior of deep-RIE MEMS sidewall surfaces. , 2018, , .		3
33	On-Chip High-Voltage Charge Pump With MEMS Post-Processed Standard 5-V CMOS on SOI for Electroosmotic Flow Micropumps. IEEE Electron Device Letters, 2018, 39, 851-854.	3.9	9
34	Increasing cell-device adherence using cultured insect cells for receptor-based biosensors. Royal Society Open Science, 2018, 5, 172366.	2.4	16
35	Test structure for electrical assessment of UV laser direct fine patterned material. , 2018, , .		0
36	Fabrication of PbS QD/Silicon Hybrid Infrared Photodiode for LSI Platform. IEEJ Transactions on Sensors and Micromachines, 2018, 138, 307-311.	0.1	5

#	ARTICLE	IF	CITATIONS
37	Odor-sensitive field effect transistor (OSFET) based on insect cells expressing insect odorant receptors. , 2017, , .		4
38	A test structure to characterize transparent electrode array platform with TFTs for bio-chemical applications. , 2017, , .		1
39	Test structures for nano-gap fabrication process development for nano-electromechanical systems. , 2017, , .		0
40	Guest Editorial Special Section on the IEEE International Conference on Microelectronic Test Structures. IEEE Transactions on Semiconductor Manufacturing, 2017, 30, 190-191.	1.7	0
41	Fabrication of PbS quantum dots and silicon device for near-infrared detection. , 2017, , .		4
42	15-year educational experience on autonomous electronic information devices by flipped classroom and try-by-yourself methods. IET Circuits, Devices and Systems, 2017, 11, 321-329.	1.4	6
43	Opportunities of CMOS-MEMS integration through LSI foundry and open facility. Japanese Journal of Applied Physics, 2017, 56, 06GA03.	1.5	16
44	A scalable, optically-driven, high-voltage switch for remote MEMS device operation fabricated with a standard CMOS process. IEICE Electronics Express, 2017, 14, 20161174-20161174.	0.8	3
45	Introduction to electronic information devices – Try-by-yourself-style lecture on autonomous electronic devices. , 2016, , .		1
46	Demonstration of 0-30V comb-drive MEMS actuator by integrated switching circuit with post-mesa-isolated standard 5V CMOS transistors. , 2016, , .		2
47	Electron-beam lithography with character projection technique for high-throughput exposure with line-edge quality control. Journal of Micro/ Nanolithography, MEMS, and MOEMS, 2016, 15, 031606.	0.9	7
48	Hotspot Liquid Microfluidic Cooling: Comparing The Efficiency between Horizontal Flow and Vertical Flow. Journal of Physics: Conference Series, 2016, 773, 012066.	0.4	8
49	Microfabricated test structures for thermal gas sensor. , 2016, , .		3
50	On-chip High-voltage Silicon Photovoltaic Cell Array Made by a CMOS Post-processed Device Isolation Method for Driving a MEMS Actuator in a Remote Manner. IEEJ Transactions on Sensors and Micromachines, 2016, 136, 24-30.	0.1	9
51	A heat balanced $\sigma$ -uncooled bolometer. Measurement Science and Technology, 2014, 25, 065101.	2.6	10
52	Remote power feed and control of MEMS with 58 V silicon photovoltaic cell made by a CMOS post-process dry release and device isolation method. , 2014, , .		8
53	Detection of micro-beads by impedance spectroscopy: Towards a wholly integrated electronic device for biological cells applications. , 2014, , .		1
54	&#x201C;MEMS de Piano&#x201D;- an experimental course of design, fabrication, and testing of MEMS oscillator. , 2014, , .		3

#	ARTICLE	IF	CITATIONS
55	A test structure of bypass diodes for on-chip high-voltage silicon photovoltaic cell array. , 2014, , .		2
56	Micro-Fluidic Channel Integration on Thick-SOI LSI Device for Biological Application.. IEEJ Transactions on Sensors and Micromachines, 2014, 134, 320-325.	0.1	1
57	Evaluation of silicon fracture strength dependence on stealth dicing layers for &#x201C;cleave-before-use&#x201D; MEMS freestanding cantilever probes. , 2013, , .		1
58	An integrated CMOS-MEMS probe having two-tips per cantilever for individual contact sensing and kelvin measurement with two cantilevers. , 2013, , .		7
59	Experimental evaluation of high voltage hold-off capability of post-process mesa-isolated series standard CMOS transistors. , 2013, , .		10
60	Power-Regulated Thermal Actuator Based on UV-Patterned Polyimides for a Ciliary Motion System. IEEJ Transactions on Sensors and Micromachines, 2013, 133, 77-84.	0.1	3
61	A stiffness-defined silicon plane bending method to realize perfectly-curved surface formation for tunable parabolic mirrors. , 2012, , .		0
62	A blur-range test structure of collimation-controller-integrated silicon shadow mask for three-dimensional surface patterning with sputtering. , 2012, , .		0
63	A CMOS compatible low temperature process for photonic crystal MEMS scanner. , 2009, , .		0
64	Test Structure for Characterizing Low Voltage Coplanar EWOD System. IEEE Transactions on Semiconductor Manufacturing, 2009, 22, 88-95.	1.7	12
65	A three-dimensional silicon shadowmask for patterning on trenches with vertical walls. , 2009, , .		4
66	High-aspect-ratio vertical surface profiler using sensitive displacement detection by optomechanical probe. Proceedings of the IEEE International Conference on Micro Electro Mechanical Systems (MEMS), 2008, , .	0.0	1
67	Wireless driven EWOD technology for a MEMS pond skater. , 2008, , .		2
68	&#x201C;silicon on PDMS&#x201D;; SOI extra thin active layer transferred to organic film for flexible applications. , 2007, , .		5
69	FPGA-Based Decentralized Control of Arrayed MEMS for Microrobotic Application. IEEE Transactions on Industrial Electronics, 2007, 54, 1926-1936.	7.9	29
70	Polarization-Transmissive Thin-Film Solar Cell with Photodiode Nanowires. , 2007, , .		0
71	Deep-Trench Vertical Si Photodiodes for Improved Efficiency and Crosstalk. IEEE Journal of Selected Topics in Quantum Electronics, 2007, 13, 386-391.	2.9	3
72	A bulk knife-edged as-deposition self-patterning structure for Greek-cross and organic thin film transistors. , 2006, , .		3

#	ARTICLE	IF	CITATIONS
73	A Highly Simple Failure Detection Method for Electrostatic Microactuators: Application to Automatic Testing and Accelerated Lifetime Estimation. IEEE Transactions on Semiconductor Manufacturing, 2006, 19, 35-42.	1.7	9
74	Design, Fabrication, and Control of MEMS-Based Actuator Arrays for Air-Flow Distributed Micromanipulation. Journal of Microelectromechanical Systems, 2006, 15, 912-926.	2.5	82
75	Deep-trench vertical si photodiode towards active-device integrated OMEMS. , 2006, , .		2
76	Contour lithography methods for DRIE fabrication of nanometreâ€“millimetre-scale coexisting microsystems. Journal of Micromechanics and Microengineering, 2006, 16, S135-S141.	2.6	25
77	A Contour-Lithography Method for Etching Nano-dimension and Large-dimension Openings. IEEJ Transactions on Sensors and Micromachines, 2006, 126, 235-240.	0.1	0
78	Advanced etching of silicon based on deep reactive ion etching for silicon high aspect ratio microstructures and three-dimensional micro- and nanostructures. Microelectronics Journal, 2005, 36, 673-677.	2.0	253
79	Accelerated life time estimation of electrostatic microactuators. , 0, , .		0
80	A MEMS array for pneumatic conveyor and its control based on distributed system. , 0, , .		8
81	A contour-lithography method for rapid and precise deep-etched nano-MEMS structure fabrication. , 0, , .		1
82	Electrical critical dimension measurement method by integration of test structure into MEMS devices. , 0, , .		2
83	Aspect Ratio Dependent Scalloping Attenuation in Drie and an Application to Low-Loss Fiber-Optical Switches. , 0, , .		18